

## AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0057] on page 13, as follows:

[0057] As stated above, in a polishing operation, the substrate carrier 10-2 is set to partly extend radially outwardly from the outer periphery of the turntable 10-1 and, thus, the diameter of the turntable 10-1 can be made small, whereby the size of the polishing apparatus can be reduced. For example, although in a conventional polishing apparatus in which an entire surface of a substrate to be polished is brought into contact with the polishing surface 10-1a of the turntable 10-1, the polishing surface is generally required to have a diameter of 600 mm for polishing a substrate having a diameter of 200 mm, the present invention makes it possible to reduce the diameter of the polishing surface for the same size substrate to 300 mm, i.e., a half of the conventional one. Thus it may be seen that the diameter of the polishing table can be allowed to be no more than substantially 1.5 times the diameter of the lower surface of the substrate carrier, which has substantially the same size as the substrate W. See for example Fig. 4.